



## Material Content Data Sheet



Halogen-Free

Sales Product Name	BTN8982TA	Issued	24. February 2022
MA#	MA005708994		
Package	PG-TO263-7-1	Weight*	1534.12 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	4.129	0.27	0.27	2691	2691
chip_2	inorganic material	silicon	7440-21-3	1.963	0.13	0.13	1280	1280
chip_3	inorganic material	silicon	7440-21-3	1.222	0.08	0.08	796	796
leadframe	inorganic material	phosphorus	7723-14-0	0.243	0.02		158	
	non noble metal	iron	7439-89-6	0.810	0.05		528	
	non noble metal	copper	7440-50-8	808.613	52.70	52.77	527085	527771
wire	non noble metal	aluminium	7429-90-5	8.284	0.54	0.54	5400	5400
encapsulation	inorganic material	zinc oxide	1314-13-2	5.855	0.38		3817	
	miscellaneous	miscellaneous	-	23.422	1.53		15267	
	plastics	epoxy resin	-	87.832	5.73		57252	
	inorganic material	silicon dioxide	60676-86-0	468.438	30.53	38.17	305346	381682
lead finish	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8498	8498
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.212	0.01	0.01	138	139
solder	non noble metal	tin	7440-31-5	0.066			43	
	noble metal	silver	7440-22-4	0.083	0.01		54	
	non noble metal	lead	7439-92-1	3.165	0.21	0.22	2063	2160
glue	plastics	Polyimide	26023-21-2	0.401	0.03	0.03	261	261
heatspreader	inorganic material	phosphorus	7723-14-0	0.032			21	
	non noble metal	iron	7439-89-6	0.106	0.01		69	
	non noble metal	copper	7440-50-8	106.210	6.92	6.93	69232	69322
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

- Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
- Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
- All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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